

190226482 MGM13S/BGM13S BOM and Mold Compound Update

PCN Issue Date: 2/26/2019 Effective Date: 5/30/2019

PCN Type: Assembly

Description of Change

Silicon Labs announces two assembly changes for BGM13S and MGM13S modules:

- 1 Three 0603 supply decoupling capacitors are being replaced with 0402 equivalent devices
- 2 A new mold compound is being introduced to maintain and guarantee product quality and reliability after decoupling capacitors are replaced.

Reason for Change

Component shortage announced by suppliers

Impact on Form, Fit, Function, Quality, Reliability

No impact on fit, function, quality or reliability. The form is changing as described in the description section.

Product Identification

Existing Part # BGM13S22F512GA-V2 BGM13S22F512GA-V2R BGM13S22F512GN-V2 BGM13S22F512GN-V2R BGM13S32F512GA-V2 BGM13S32F512GA-V2R BGM13S32F512GN-V2 BGM13S32F512GN-V2R MGM13S02F512GA-V2 MGM13S02F512GA-V2R MGM13S02F512GN-V2 MGM13S02F512GN-V2R MGM13S12F512GA-V2 MGM13S12F512GA-V2R MGM13S12F512GN-V2 MGM13S12F512GN-V2R BGX13S22GA-V21 BGX13S22GA-V21R

Last Date of Unchanged Product: 5/30/2019

Qualification Samples

Available upon request.

Customer Response

Lack of acknowledgment of the PCN within 30 days constitutes acceptance of the change, Ref. JEDEC-J-STD-046.

To request further data or inquire about this notification, please contact your Silicon Labs sales representative. A list of Silicon Labs sales representatives is available at http://www.silabs.com.

Customers may approve early PCN acceptance by emailing approval, along with PCN # to PCNEarlyAcceptance@silabs.com

User Registration

Register today to create your account on Silabs.com. Your personalized profile allows you to receive technical document updates, new product announcements, "how-to" and design documents, product change notices (PCN) and other valuable content available only to registered users. http://www.silabs.com/profile

Qualification Data

See attached Qualification Report.



BGM13S Qualification Report

The information contained in this document is PROPRIETARY to Silicon Labs and shall not be reproduced or used in part or whole without Silicon Labs' written consent. The document is uncontrolled if printed or electronically saved.

Part Rev C, TSMC Fabrication, SPIL Assembly except as noted							
Test Name	Test Condition	Qualification	Lot ID or Start	Fail/Pass or End	Notes	Summary	Status
	erated Environment Stress Te	sts					
HAST	JA110		Q043729	0/25	1		
	110°C, 85%RH	3 lots, N=>25	Q043730	0/25	1	3 lots	Pass
	Vcc=1.9V, 264 hours		Q043731	0/25	1	0/75	
Temp Cycle	JA104		Q043706	0/25	1		
	Cond B: -55°C to 125°C	3 lots, N=>25	Q043707	0/25	1	3 lots	Pass
	700 cycles		Q043708	0/25	1	0/75	
HTSL	JA103		Q043703	0/30	1		
	150°C, 1000hr	3 lots, N=>25	Q043704	0/30	1	3 lots	Pass
			Q043705	0/30	1	0/90	
Test Group B – Accel	erated Lifetime Simulation Te	sts					
HTOL	JA108	T	Q040471	0/80	2		
	T _J ≥ 125°C, Dynamic	3 lots, N=>77	Q041124	0/80	2	3 lots	Pass
	Vcc=1.9V, 1000 hours		Q040650	0/79	2	0/239	
LTOL	JA108						
	T _A = -10°C, Dynamic	1 lot, N=>32	Q040451	0/80	2	1 lots	Pass
	Vcc=1,9V, 1000 hours					0/80	
ELFR	JA108		Q040450	0/505	2	100	
	T, ≥ 125°C, Dynamic	3 lots, N=>500	Q040472	0/516	2	3 lots	Pass
	Vcc=1.9V, 48 hours		Q040651	0/515	2	0/1536	
NVM Endurance,	JA117		Q040213	0/40	2	0.1000	
Retention and Operating	ng 25°C	3 lots, N=>39	Q040274	0/40	2	3 lots	Pass
Life	500 hours	5 1013, 14-2-05	Q040278	0/40	2	0/120	F 033
NVM Endurance.	JA117		Q040214	0/40	2	0/120	
Retention and Operating	ng 150°C	3 lots. N=>39	Q040275	0/40	2	3 lots	Pass
Life	1000 hours	3 1013, 14-233	Q040279	0/40	2	0/120	r daa
Test Group E - Electr			0040275	0.40	-	0/120	
ESD-HBM			_				
	JS-001	filed New 2	Q043583			2 kV	01 0
	1	1 lot, N=>3	Q043583			2 KV	Class 2
ESD-CDM	10.000	_					
	JS-002	4 144 11-0	00/2522			50011	Ø1 III
		1 lot, N=>3	Q043582			500 V	Class III
Latch Up	JESD78	_					
	±200mA	1 lot, N=>3	Q043580	125 °C			Pass
	Overvoltage = 2.85V						

¹ silabs.com | BGM13-Product_Qualification_Report



BGM13S Qualification Report

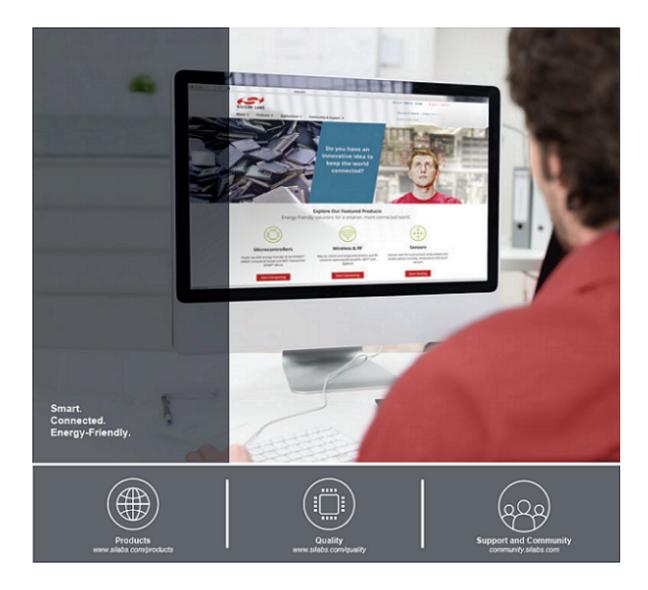
The information contained in this document is PROPRIETARY to Silicon Labs and shall not be reproduced or used in part or whole without Silicon Labs' written consent. The document is uncontrolled if printed or electronically saved.

Part Rev C, TSMC Fabrication, SPIL Assembly except as noted								
Test Name	Test Condition	Qualification	Lot ID or Start	Fail/Pass or End		Summary	Status	

Notes:

- 1. Parts are Pre-conditioned at MSL3/260°C
- 2. Leveraged die family data

This report applies to the following part numbers:							
BGM13S12F512GA-V2	BGM13S12F512GA-V2R	BGM13S12F512GN-V2	BGM13S12F512GN-V2R	BGM13S22F512GA-V2			
BGM13S22F512GA-V2R	BGM13S22F512GN-V2	BGM13S22F512GN-V2R	BGM13S32F512GA-V2	BGM13S32F512GA-V2R			
BGM13S32F512GN-V2	BGM13S32F512GN-V2R	MGM13S02F512GA-V2	MGM13S02F512GA-V2R	MGM13S02F512GN-V2			
MGM13S02F512GN-V2R	MGM13S12F512GA-V2	MGM13S12F512GA-V2R	MGM13S12F512GN-V2	MGM13S12F512GN-V2R			
BGX13S22GA-V21	BGX13S22GA-V21R						



Disclaimer

Silicon Labs intends to provide customers with the latest, accurate, and in-depth documentation of all peripherals and modules available for system and software implementers using or intending to use the Silicon Labs products. Characterization data, available modules and peripherals, memory sizes and memory addresses refer to each specific device, and "Typical" parameters provided can and do vary in different applications. Application examples described herein are for illustrative purposes only. Silicon Labs reserves the right to make changes without further notice and limitation to product information, specifications, and descriptions herein, and does not give warranties as to the accuracy or completeness of the included information. Silicon Labs shall have no liability for the consequences of use of the information supplied herein. This document does not imply or express copyright licenses granted hereunder to design or fabricate any integrated circuits. The products are not designed or authorized to be used within any Life Support System without the specific written consent of Silicon Labs. A "Life Support System" is any product or system intended to support or sustain life and/or health, which, if it fails, can be reasonably expected to result in significant personal injury or death. Silicon Labs products are not designed or authorized for military applications. Silicon Labs products shall under no circumstances be used in weapons of mass destruction including (but not limited to) nuclear, biological or chemical weapons, or missiles capable of delivering such weapons.

Trademark Information

Silicon Laboratories Inc.®, Silicon Laboratories®, Silicon Labs®, SiLabs® and the Silicon Labs logo®, Bluegiga®, Bluegiga Logo®, Clockbuilder®, CMEMS®, DSPLL®, EFM®, EFM32®, EFR, Ember®, Energy Micro, Energy Micro logo and combinations thereof, "the world's most energy friendly microcontrollers", Ember®, EZLink®, EZRadio®, EZRadioPRO®, Gecko®, ISOmodem®, Micrium, Precision32®, ProSLIC®, Simplicity Studio®, SiPHY®, Telegesis, the Telegesis Logo®, USBXpress®, Zentri and others are trademarks or registered trademarks of Silicon Labs. ARM, CORTEX, Cortex-M3 and THUMB are trademarks or registered trademarks of ARM Holdings. Keil is a registered trademark of ARM Limited. All other products or brand names mentioned herein are trademarks of their respective holders.



Silicon Laboratories Inc. 400 West Cesar Chavez Austin, TX 78701